

# ABSTRACT

An object of the invention is to provide a semiconductor polishing composition that can efficiently polish a semiconductor device with high accuracy while preventing fumed silica from being agglomerated and without causing a polishing flaw in the semiconductor device. Fumed silica of which a bulk density of powder before dispersed is 50 g/L or more and less than 100 g/L, is used as abrasive grains. The bulk density is more preferably 75 g/L or more and 85 g/L or less. This makes it possible to enhance a dispersion state of the fumed silica, and to realize reduction in transportation cost.